

ABSTRACT

TRANSFER MOLDING METHOD AND SYSTEM FOR ELECTRONIC DEVICES

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A method and system for molding an electronic device which is located next to a molding cavity and clamped to the molding cavity during molding, comprising providing molding compound in a mold supply pot, discharging the molding compound from the mold supply pot into a runner, and distributing the molding
10 compound through the runner into the molding cavity in order to fill the molding cavity. A movable surface comprised in the molding cavity is positioned to form a first gap between the movable surface and the electronic device when the molding cavity is being filled. After filling the molding cavity with molding compound, the movable surface is driven to form a second gap between the
15 movable surface and the electronic device which is smaller than the first gap, thereby compressing the molding compound in the molding cavity. A molded electronic device thus produced is then separated from the molding cavity.

(FIG. 1B)

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